



SILICON 850

THERMAL PASTE

FEATURES:

- Thermal Conductivity: 13,4 W/m*K
- Thermal Impedance: 0,001 °C*in²/W
- Volume: 2 g / 0,2 ml
- Temperature range: -30 – 250 °C
- Non-Conductive/Curing/Corrosive

PRODUCT SPECIFICATION:

Color	Grey
Density at 25°C (g/ml)	2,1
Viscosity at 1rpm (mPa s)	90000
Thermal conductivity	13,4 W/m*K
Thermal Impedance	0,001 °C *in ² /W
Weight loss after 96 hours at 100°C	0,15%
Permittivity at 106Hz	2,4
Volume resistivity	4,0 x 10 ¹³ (Ohm*cm)
Dielectric strength	3,3 KV/mm
Working temperature	-30~250 °C

